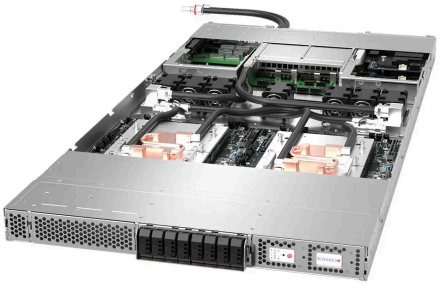
Arm-based (ARS) | 1U Rackmount | GPU Server

Supermicro ARS-111GL-DNHR-LCC

Arm-based (ARS) · 1U Rackmount · GPU Server · Liquid Cooling Server

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Form Factor **1U Rackmount**	CPU **NVIDIA 72-core NVIDIA Grace CPU on GH200 Grace Hopper™ Superchip**
GPU **1 onboard GPU**	Memory **Onboard Memory**

Key Features

- High density 1U 2-node GPU system with Integrated NVIDIA® H100 GPU (1 per Node)
- NVIDIA Grace Hopper™ Superchip (Grace CPU and H100 GPU)
- NVLink® Chip-2-Chip (C2C) high-bandwidth, low-latency interconnect between CPU and GPU at 900GB/s
- Up to 576GB of coherent memory per node including 480GB LPDDR5X and 96GB of HBM3 for LLM applications
- 2x PCIe 5.0 x16 slots per node supporting NVIDIA BlueField®-3 or ConnectX®-7
- 7 Hot-Swap Heavy Duty Fans with Optimal Fan Speed Control
- This system supports two E1.S drives directly from the processor only.

Form Factor	1U Rackmount
Platform	Arm-based (ARS)
CPU	NVIDIA 72-core NVIDIA Grace CPU on GH200 Grace Hopper™ Superchip
Max GPU Count	1 onboard GPU
Supported GPU	NVIDIA: H100 Tensor Core GPU on GH200 Grace Hopper™ Superchip
Memory	Onboard Memory Up to 480GB ECC LPDDR5X
Drive Bays	Default: Total 4 bays4 front fixed E1.S NVMe drive bays
Fans	Up to 7 Removable heavy-duty 4cm Fan(s)
Power Supply	2x 2700W Redundant Titanium Level (96%) power supplies

Full Specifications — ARS-111GL-DNHR-LCC

Motherboard

Motherboard	ARS-111GL-DNHR-LCC Super G1SMH-G

Processor (per Node)

CPU	NVIDIA 72-core NVIDIA Grace CPU on GH200 Grace Hopper™ Superchip
Core Count	Up to 72C/72T; Up to 117MB Cache
Note	Supports up to 2000W TDP CPUs (Liquid Cooled)

GPU (per Node)

Max GPU Count	1 onboard GPU
Supported GPU	NVIDIA: H100 Tensor Core GPU on GH200 Grace Hopper™ Superchip View GPU Options
CPU-GPU Interconnect	NVIDIA NVLink®-C2C
GPU-GPU Interconnect	PCIe

System Memory (per Node)

Memory	Onboard Memory Up to 480GB ECC LPDDR5X Additional GPU Memory: Up to 96GB ECC HBM3

On-Board Devices (per Node)

Chipset	NVIDIA System on Chip
Network Connectivity	View AOC Options

Input / Output (per Node)

LAN	1 RJ45 1 GbE Dedicated BMC LAN port
USB	2 ports (rear)
Video	1 mini-DP port

System BIOS

BIOS Type	AMI 64MB SPI Flash EEPROM

Management

Power configurations	Power-on mode for AC power recovery ACPI Power Management

PC Health Monitoring

CPU	Monitors for CPU Cores, Chipset Voltages, Memory
Fan	Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control
Temperature	Monitoring for CPU and chassis environment Thermal Control for fan connectors

Certifications

Operating Systems	RHEL 9.2 View all OS Compatibility and Certification Matrix

Chassis

Form Factor	1U Rackmount
Model	CSE-GP102TS-R000NDFP

Dimensions and Weight

Height	1.75" (44 mm)
Width	17.33" (440 mm)
Depth	37" (940 mm)
Package	9.5" (H) x 28" (W) x 48" (D)
Weight	Gross Weight: 65.5 lbs (29.7 kg) Net Weight: 48.5 lbs (22 kg)
Available Color	Silver

Expansion Slots (per Node)

PCI-Express (PCIe) Configuration	Default2 PCIe 5.0 x16 FHFL slots View AOC Options

Drive Bays / Storage (per Node)

Drive Bays Configuration	Default: Total 4 bays4 front fixed E1.S NVMe drive bays
M.2	2 M.2 NVMe slots (M-key) View M.2 Options

System Cooling

Fans	Up to 7 Removable heavy-duty 4cm Fan(s)
Liquid Cooling	Direct to Chip (D2C) Cold Plate (optional)

Power Supply

2x 2700W Redundant Titanium Level (96%) power supplies

Dimension (WxHxL)	73.5 x 40 x 185 mm
Input	2700W: 200-240Vac / 50-60Hz 2700W: 240-240Vdc / 50-60Hz (for CQC only)
+12V	Max: 225A / Min: 0A (200Vac-240Vac) Max: 225A / Min: 0A (240Vdc-240Vdc)
12V SB	Max: 4A / Min: 0A
Output Type	Backplanes (gold finger)

Operating Environment

Environmental Spec.	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)